

# **JL7096M Datasheet**

**Zhuhai Jieli Technology Co.,LTD**

**Version 1.0**

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## Revision History

Date	Revision	Description
2025.12.04	V1.0	Initial Release



# Table of Contents

<b>Revision History</b> .....	<b>1</b>
<b>Table of Contents</b> .....	<b>2</b>
<b>JL7096M Features</b> .....	<b>3</b>
<b>1 Block Diagram</b> .....	<b>4</b>
<b>2 Pin Definition</b> .....	<b>5</b>
2.1 Pin Assignment .....	5
2.2 Pin Description .....	6
<b>3 Electrical Characteristics</b> .....	<b>8</b>
3.1 Absolute Maximum Ratings .....	8
3.2 ESD Ratings .....	8
3.3 PMU Characteristics .....	8
3.4 Battery Charge .....	9
3.5 IO Characteristics .....	9
3.6 Audio DAC Characteristics .....	10
3.7 Audio ADC Characteristics .....	12
3.8 BT Characteristics .....	13
<b>4 Package Information</b> .....	<b>14</b>
4.1 QFN32_4x4mm .....	14
<b>5 IC Marking Information</b> .....	<b>15</b>
<b>6 Solder-Reflow Condition</b> .....	<b>16</b>

# JL7096M Features

## SYSTEM

- Dual Core 32bit DSP 192MHz
- With IEEE754 Single precision FPU
- Support FFT/MATRIX/MATH
- 2 x I-cache and D-cache
- Support SDTAP/EMU
- On-chip SRAM 320kbyte
- Support MMU
- Support MPU
- Built-In Flash
- 24MHz crystal oscillator
- Internal RC oscillator,PLL

## DSP Audio Processing

- SBC/AAC/LDAC/LHDC/LC3/CVSD/mSBC codec
- mSBC voice codec supported for BT phone
- PLC for voice processing
- Single/Multi MIC ENC
- Multi-band DRC
- Multi-band EQ
- Support spatial sound
- Support assistive listening

## Audio

- 2 x 24bit DAC
  - ❖ SNR 113dB
  - ❖ Noise 1.2uVrms
  - ❖ Support differential mode
  - ❖ Sampling rate 8~384kHz
- 3 x 24bit ADC
  - ❖ SNR 100dB
  - ❖ Sampling rate 8~192kHz
- I<sup>2</sup>S/TDM/PDM AUDIO Master/Slave interface

## Bluetooth

- Dual-mode BT6.0 with LE Audio (DN Q332415)
- Support AoA/AoD
- Support LE audio BIS/CIS
- Maximum transmitting power 13dBm
- Receiver sensitivity

- ❖ -97dBm @BR
- ❖ -97dBm @EDR  $\pi/4$  DQPSK
- ❖ -89dBm @EDR 8DPSK

## Peripherals

- 1 x Full speed USB
- 6 x Multi-function 32bit timer
- 3 x UART interface
- 1 x I<sup>2</sup>C Master/Slave interface
- 3 x SPI Master/Slave interface
- 1 x 10bit ADC(10 Channels)
- 15 x GPIO Support function remapping
- 3 x LP\_Touch with low power wake up

## PMU

- Integrated battery charger up to 180mA
- 1 x Buck DC-DC converter
- Support temperature sensor
- VPWR range 4.5V to 5.5V
- VBAT range 2.7V to 5.5V
- IOVDD range 2.7V to 3.6V

## Packages

- QFN32(4\*4mm)

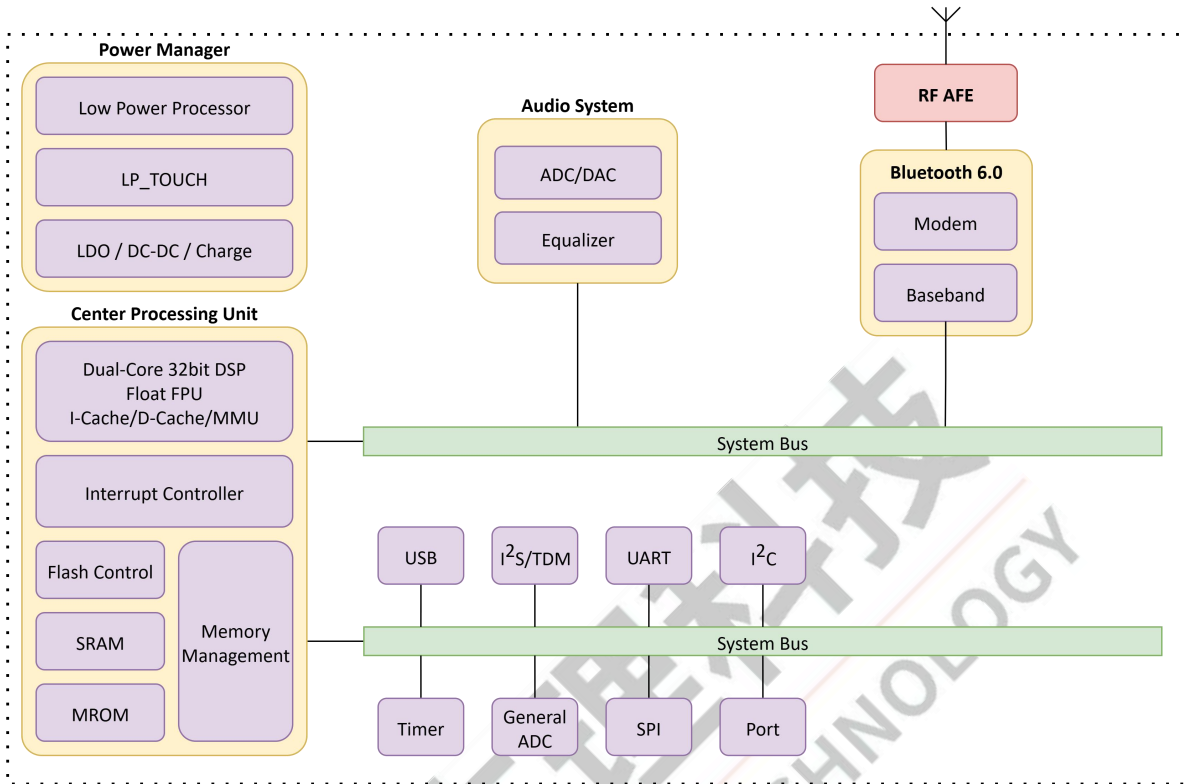
## Temperature

- Operating temperature
  - TC = -20°C to +85°C (standard range)
  - TC = -40°C to +105°C (extended range)
- Storage temperature -65°C to +150°C

## Applications

- Bluetooth Dongle

# 1 Block Diagram



**Figure 1-1 JL7096M Block Diagram**

## 2 Pin Definition

### 2.1 Pin Assignment

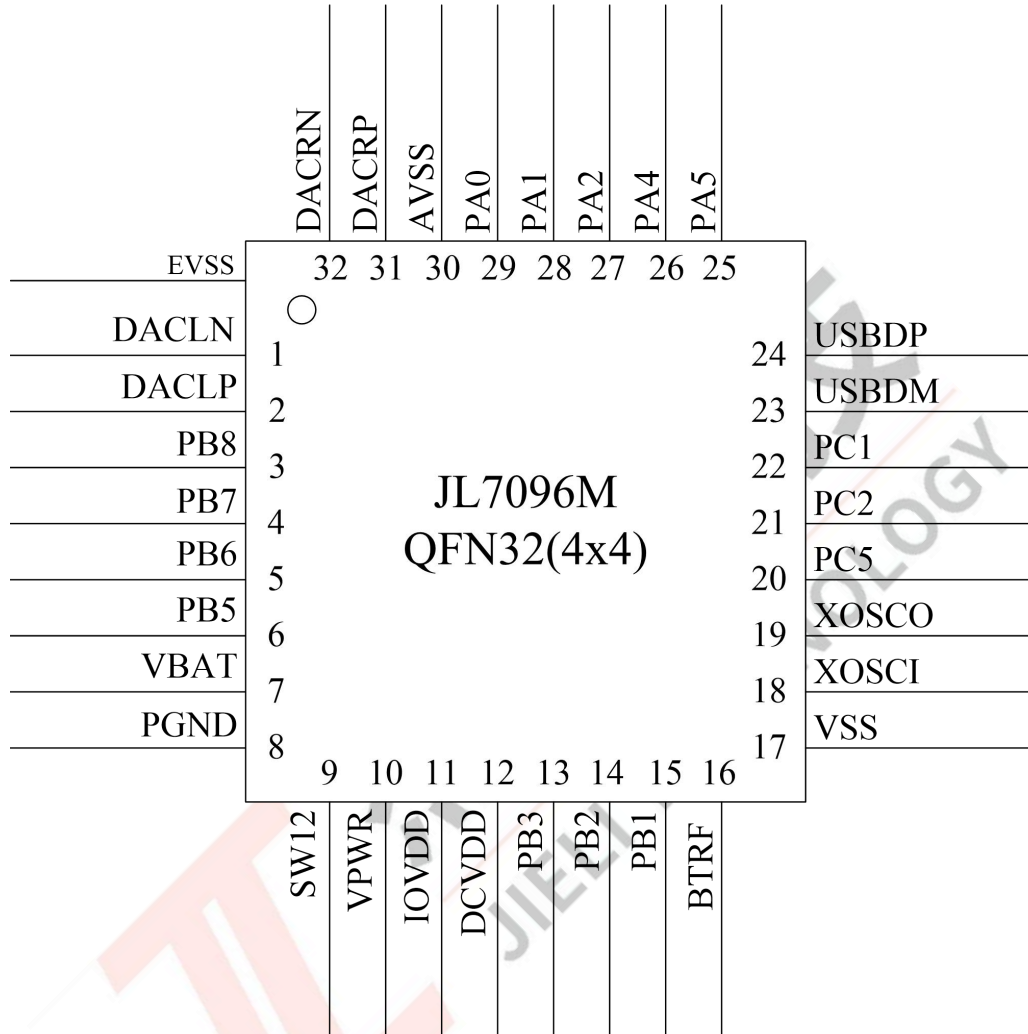


Figure 2-1 JL7096M Pin Assignment

## 2.2 Pin Description

**Table 2-2-1 JL7096M Pin Description**

Pin No.	Name	Type	IO Initial State	Description
1	DACLN	O	--	Left Channel DAC Negative Output
2	DACLP	O	--	Left Channel DAC Positive Output
3	PB8	I/O	Z	AIN_CP0(Audio ADC Positive Input)
4	PB7	I/O	Z	AIN_CN0(Audio ADC Negative Input)
5	PB6	I/O	Z	LVD(External Low Voltage Detection Input) AIN_BP1(Audio ADC Positive Input) MICBIASC(MIC Bias Output)
6	PB5	I/O	Z	AIN_BN1(Audio ADC Negative Input) ADC5(ADC Input Channel 5)
7	VBAT	P	--	Battery Input
8	PGND	P	--	Ground of Buck DC-DC converter
9	SW12	P	--	Buck DCDC12 Switch Port
10	VPWR	I/O	Z	Charge Power Input
11	IOVDD	P	--	IO Power
12	DCVDD	P	--	Buck DCDC12 Output Power
13	PB3	I/O	Z	ADC3(ADC Input Channel 3) LP_TOUCH3(TOUCH_CH3)
14	PB2	I/O	Z	ADC2(ADC Input Channel 2) LP_TOUCH2(TOUCH_CH2)
15	PB1	I/O	10kΩ Pull-up	ADC1(ADC Input Channel 1) LP_TOUCH1(TOUCH_CH1) Hold down 0 to reset
16	BTRF	RF	--	Bluetooth RF Antenna
17	VSS	G	--	Ground
18	XOSCI	I	--	Crystal Oscillator Input
19	XOSCO	O	--	Crystal Oscillator Output
20	PC5	I/O	Z	ADC11(ADC Input Channel 11)
21	PC2	I/O	Z	ADC8(ADC Input Channel 8)
22	PC1	I/O	Z	ADC7(ADC Input Channel 7)
23	USBDM	I/O	15kΩ Pull-down	USB Negative Data ADC15(ADC Input Channel 15)
24	USBDP	I/O	15kΩ Pull-down	USB Positive Data ADC14(ADC Input Channel 14)
25	PA5	I/O	Z	AIN_BP0(Audio ADC Positive Input)
26	PA4	I/O	Z	AIN_BN0(Audio ADC Negative Input) AIN_AN1(Audio ADC Negative Input)
27	PA2	I/O	Z	AIN_AN0(Audio ADC Negative Input)

Pin No.	Name	Type	IO Initial State	Description
28	PA1	I/O	Z	AIN_AP0(Audio ADC Positive Input)
29	PA0	I/O	Z	ADC6(ADC Input Channel 6) MICBIASA(MIC Bias Output) MICLDO(MIC Bias LDO Output)
30	AVSS	G	--	Audio Ground
31	DACRP	O	--	Right Channel DAC Positive Output
32	DACRN	O	--	Right Channel DAC Negative Output

**Note**

- 1.IO initial state abbreviations Z--High resistance, H--High level, L--Low level, X--May be changed during power on.
- 2.Timer, UART, I<sup>2</sup>C, I<sup>2</sup>S, SPI functions can be remapped to any I/O.

**Table 2-2-2 Pin Types Description**

Pin Type	Description	Pin Type	Description
P	Power	I/O	Input or Output
G	Ground	I	Input
RF	RF antenna	O	Output

### 3 Electrical Characteristics

#### 3.1 Absolute Maximum Ratings

**Table 3-1 Absolute Maximum Ratings**

Symbol	Parameter	Min	Max	Unit
Topt	Operating temperature	-20	+85	°C
Tstg	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	5.5	V
VPWR		-0.3	6	V
IOVDD		-0.3	3.6	V
DCVDD		-0.3	1.25	V
GPIO	Input voltage of GPIO	-0.3	3.6	V

**Note**

1. Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device.

#### 3.2 ESD Ratings

**Table 3-2 ESD Ratings**

Parameter	Typ	Test pin	Reference standard
Human Body Mode	±4kV	All pins	JEDEC EIA/JESD22-A114
Machine Mode	±300V	All pins	JEDEC EIA/JESD22-A115
Charge Device Model	±2kV	All pins	ANSI/ESDA/JEDEC JS-002-2022

#### 3.3 PMU Characteristics

**Table 3-3 PMU Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VBAT	Power supply	--	2.7	3.7	5.5	V
VPWR	Power supply	--	4.5	5.0	5.5	V
<b>Operating mode</b>						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IOVDD	Voltage output	--	--	3	--	V
	Loading current	IOVDD=3.0V@VBAT = 3.7V or VPWR=5V	--	--	120	mA
DCVDD	Voltage output	--	--	1.15	--	V
	Loading current	DCVDD=1.15V@IOVDD=3.0V in LDO mode	--	--	120	mA
		DCVDD=1.15V@VBAT=3.7V in DCDC mode	--	--	120	mA
<b>Low Power mode</b>						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IOVDD	Loading current	IOVDD=3.0V@VBAT = 3.7V or VPWR=5V	--	--	10	mA

### 3.4 Battery Charge

**Table 3-4 Charger Characteristics**

Symbol	Parameter	Min	Typ	Max	Unit
VPWR	Charge Input Voltage	4.5	5	5.5	V
CV	CV Mode Voltage Accuracy	4.175	4.2	4.225	V
		4.325	4.35	4.375	V
CC	CC Mode Current	15	--	180	mA
$I_{end}$	End Of Charge Current	1.5	--	18	mA
$V_{Trickl}$	Trickle Charge Voltage	--	3	--	V

### 3.5 IO Characteristics

**Table 3-5 IO Characteristics**

Input Characteristics						
Symbol	Parameter	Conditions	IO	Min	Max	Unit
$V_{IL}$	Low-Level Input Voltage	IOVDD = 3.0V	PA0~PA2,PA4,PA5 PB1~PB3,PB5~PB8 PC1,PC2,PC5 USBDP USBDM VPWR	-0.3	1.4	V
$V_{IH}$	High-Level Input Voltage	IOVDD = 3.0V	PA0~PA2,PA4,PA5 PB1~PB3,PB5~PB8 PC1,PC2,PC5 USBDP USBDM	1.7	3.3	V
		IOVDD = 3.0V	VPWR	1.7	5.5	V
Output Characteristics						
Symbol	Parameter	Conditions	IO	Typ	Unit	
$ I_{OL} $	Output Current	IOVDD = 3.0V Voutput = 0.3V	PA0~PA2,PA4,PA5 PB1~PB3,PB5~PB8 PC1,PC2,PC5	4(HD=0) 8(HD=1) 16(HD=2) 32(HD=3)	mA	
		IOVDD = 3.0V Voutput = 0.3V	USBDP USBDM	8	mA	
		IOVDD = 3.0V Voutput = 0.3V	VPWR	2	mA	
$ I_{OH} $	Output Current	IOVDD = 3.0V Voutput = 2.7V	PA0~PA2,PA4,PA5 PB1~PB3,PB5~PB8 PC1,PC2,PC5	4(HD=0) 8(HD=1) 16(HD=2) 32(HD=3)	mA	

		IOVDD = 3.0V Voutput = 2.7V	USBDP USBDM	8	mA
		IOVDD = 3.0V Voutput = 2.7V	VPWR	2	mA
Internal Resistance Characteristics					
Symbol	Parameter	Conditions	IO	Typ	Unit
R <sub>pu</sub>	Pull-up Resistance	IOVDD = 3.0V	PA0~PA2,PA4,PA5 PB1~PB3,PB5~PB8 PC1,PC2,PC5 VPWR	10k(PU=1) 100k(PU=2) 1M(PU=3)	Ω
			USBDP	1.5k	Ω
			USBDM	180k	Ω
R <sub>pd</sub>	Pull-down Resistance	IOVDD = 3.0V	PA0~PA2,PA4,PA5 PB1~PB3,PB5~PB8 PC1,PC2,PC5 VPWR	10k(PD=1) 100k(PD=2) 1M(PD=3)	Ω
			USBDP USBDM	15k	Ω

**Note**

 1.Internal pull-up/pull-down resistance accuracy  $\pm 20\%$ 

### 3.6 Audio DAC Characteristics

**Table 3-6 Stereo DAC Characteristics**

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Input Sample Rate	--	8	--	384	kHz
SNR <sup>①</sup>	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	113	--	dB
Dynamic Range	Differential Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	106	--	dB
THD+N	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=32Ω	--	-85	--	dB

Parameter	Conditions	Min	Typ	Max	Unit
Noise Floor	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	2.7	--	uVrms
Noise Floor with MUTE	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	1.2	--	uVrms
Max Output Power	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=16Ω THD+N < 1%	--	20	30	mW

**Note**

- ① SNR is the ratio of output level with a 1kHz full-scale input to output level with MUTE on.

### 3.7 Audio ADC Characteristics

**Table 3-7 Audio ADC Characteristics**

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Output Sample Rate	--	8	--	192	kHz
SNR	Differential input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	100	--	dB
	Single-ended input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	93	--	dB
Dynamic Range	Differential input Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	100	--	dB
	Single-ended input Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	93	--	dB
THD+N	Differential input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	-85	--	dB
	Single-ended input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	-83	--	dB
Analogue Gain	--	-6	--	27	dB
Max Input Level	Differential input Mode ADC gain=0dB	--	0.56	--	Vrms
	Single-ended input Mode ADC gain=0dB	--	0.28	--	Vrms

### 3.8 BT Characteristics

#### 3.8.1 Transmitter

Table 3-8-1 Transmitter characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Maximum RF Transmit Power	BR	--	10	13	dBm
Maximum RF Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	10	--	dBm
Relative Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	3	--	dB
Maximum RF Transmit Power	BLE-1Mbps	--	10	13	dBm

#### 3.8.2 Receiver

Table 3-8-2 Receiver characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Sensitivity	BR	--	-97	--	dBm
	EDR $\pi/4$ DQPSK	--	-97	--	dBm
	EDR 8DPSK	--	-89	--	dBm
	BLE-1Mbps	--	-99.5	--	dBm
	BLE-2Mbps	--	-96.5	--	dBm

## 4 Package Information

### 4.1 QFN32\_4×4mm

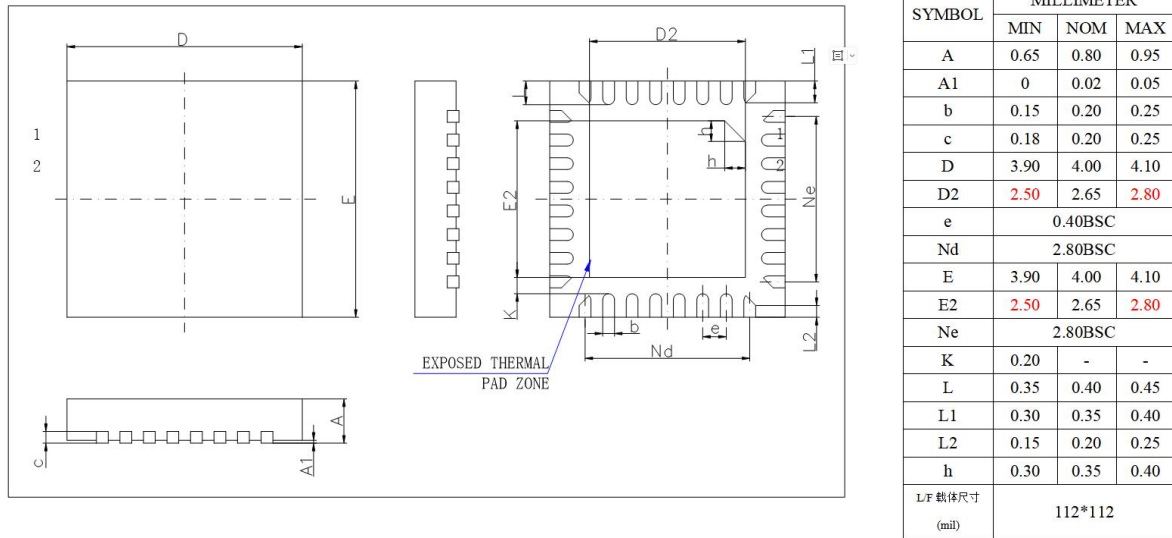


Figure 4-1 JL7096M Package

## 5 IC Marking Information

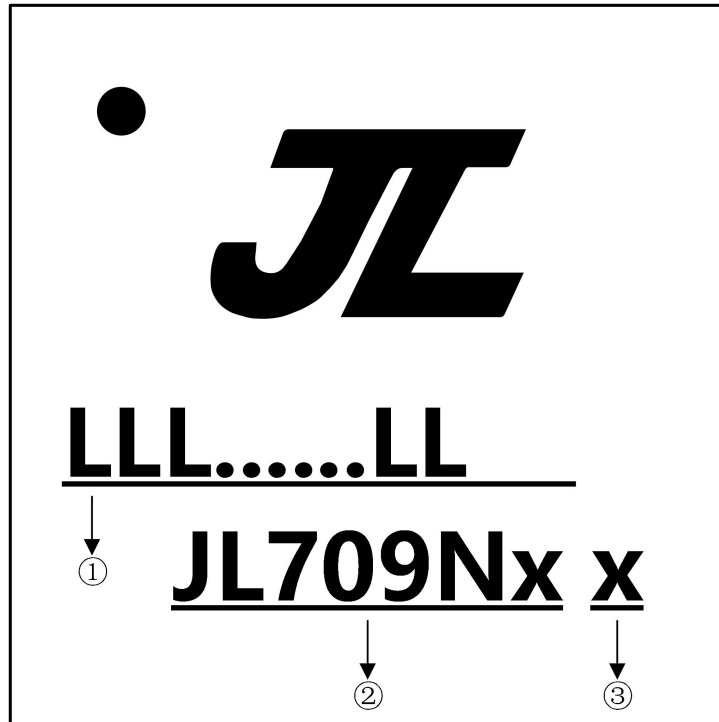


Figure 5-1 JL7096M Package Outline

- ① LLL.....LL LOT No. , It contains 7 to 18 alphanumerics
- ② JL709Nx Chip Model
- ③ x Built-in flash size
  - 0 No Flash Memory
  - 2 2Mbit Flash
  - 4 4Mbit Flash
  - 8 8Mbit Flash
  - 6 16Mbit Flash
  - 3 32Mbit Flash

## 6 Solder-Reflow Condition

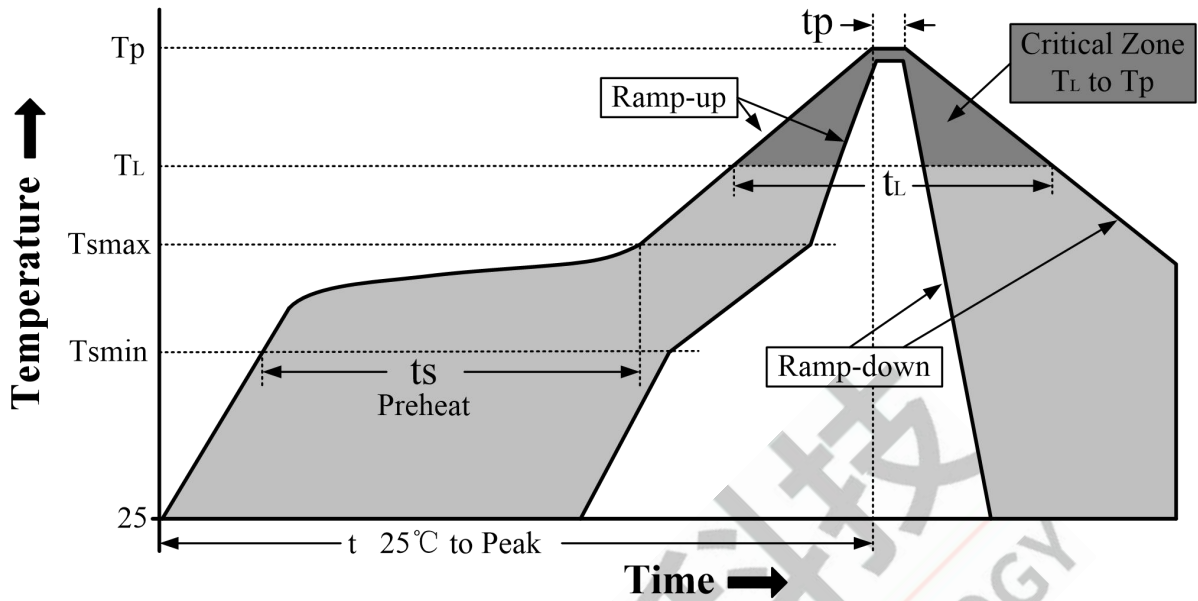


Figure 6-1 Classification Reflow Profile

Table 6-1 Classification Profiles

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak	Temperature Min ( $T_{smin}$ )	100°C	150°C
	Temperature Max ( $T_{smax}$ )	150°C	200°C
	Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60-120 seconds	60-180 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )		3°C/second max	3°C/second max
Liquidous temperature ( $T_L$ )		183°C	217°C
Time ( $t_L$ ) maintained above $T_L$		60-150 seconds	60-150 seconds
Peak package body temperature ( $T_p$ )		See Table 6-2	See Table 6-3
Time within 5°C of actual Peak Temperature ( $t_p$ ) <sup>2</sup>		10-30 seconds	20-40 seconds
Ramp-down rate ( $T_p$ to $T_L$ )		6°C/second max	6°C/second max
Time 25°C to peak temperature		6 minutes max	8 minutes max

**Note**

- 1.All temperatures refer to topside of the package, measured on the package body surface
- 2.Time within 5°C of actual peak temperature ( $t_p$ ) specified for the reflow profiles is a “supplier” and “user” maximum.

Table 6-2 SnPb Classification Temperature

Package Thickness	Volume mm <sup>3</sup>	Volume mm <sup>3</sup>
	< 350	≥ 350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

**Table 6-3 Pb-free - Classification Temperature**

Package Thickness	Volume mm <sup>3</sup> < 350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> > 2000
< 1.6mm	260°C	260°C	260°C
1.6 mm - 2.5mm	260°C	250°C	245°C
> 2.5mm	250°C	245°C	245°C

**Note**

1.\*Tolerance The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C.For example 260°C+0°C)at the rated MSL level.